



ABSTRACT

The LM61430-Q1 evaluation module (EVM) is designed to help customers evaluate the performance of the LM61430-Q1 synchronous, step-down voltage converter. This EVM implements the LM61430-Q1 in a 14-pin wettable flanks Hotrod™ package, as shown in Table 1-1. The EVM is configured for 5-V output voltage with DC load current up to 3 A. The EVM is optimized for small solution size and low noise.

Table 1-1. Device and Package Configurations

CONVERTER	IC	PACKAGE
U1	LM61430-Q1	14-pin wettable flanks Hotrod 4.0-mm × 3.5-mm × 1.0-mm package

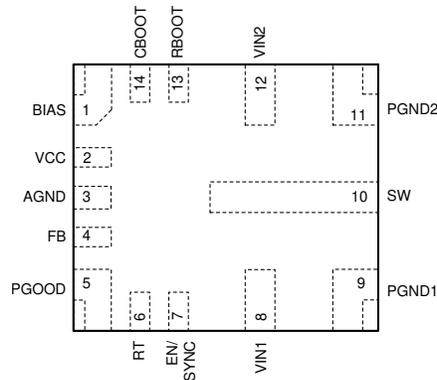


Table of Contents

1 Quick Start	2
2 Detailed Descriptions	2
3 Schematic	3
4 Board Layout	4
5 Thermal Performance	5
5.1 Additional Performance Curves.....	5
6 Bill of Materials (BOM)	6

List of Figures

Figure 3-1. LM61430EVM-AS-2MHZ Schematic.....	3
Figure 4-1. Top 3-D View.....	4
Figure 4-2. Top Layer.....	4
Figure 4-3. Signal Layer 1 – Ground Plane.....	4
Figure 4-4. Signal Layer 2 – Routing.....	4
Figure 4-5. Bottom Layer.....	4
Figure 4-6. Bottom 3-D View.....	4
Figure 5-1. Thermal Performance.....	5

List of Tables

Table 1-1. Device and Package Configurations.....	1
Table 6-1. LM61430EVM-AS-2MHZ Bill of Materials.....	6

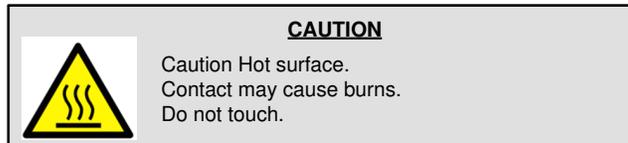
Trademarks

Hotrod™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

1 Quick Start

1. Connect the voltage supply between the VIN_EMI and GND_EMI pins.
2. Connect the load of the converter between the VOUT and GND connectors.
3. Set the supply voltage at an appropriate level between 6 V to 36 V. Set the current limit of the supply above 3 A. The 6-V minimum makes sure there is sufficient headroom on maximum dropout voltage.
4. Turn on the power supply. Monitor the output voltage with sense points. The maximum load current must be below 3 A with the LM61430-Q1.

See [Figure 4-1](#) for connector locations.



2 Detailed Descriptions

This section describes the connectors on the EVM and how to properly set up the EVM.

VOUT	5-V output voltage of the converter Connect the loading device to the board with short and thick wires.
GND	Ground of the converter Connect to supply and load grounds with short and thick wires. "Clip-on" GND connectors are for signal measurement and probing.
VIN_EMI	Input voltage to input filter of the converter Connect with short and thick wires.
GND_EMI	Ground return for the input filter Connect with short and thick wires.
CLK	For synchronization clock input The buck PWM output is synchronized to the external clock when applied.
EN	To monitor the EN pin or input EN control signal
PG	To monitor the PGOOD/RESET pin The PGOOD pin of the device is an open-drain output and it is pulled up to V _{OUT} when in regulation and pulled to GND when not.
VINJ	To aid when making bode plots There is injection resistor, R _{inj} , between VOUT and this node. Transformer-based stimulus can be applied across R _{inj} when taking measurements for bode plots.
VOUTS	Kelvin sensing for VOUT For accurate load and line regulation measurements, VOUTS must be utilized. There is non-negligible I-R drop at maximum load between the output capacitor and VOUT connector.

3 Schematic

The bill of materials for the EVM is tabulated in [Table 6-1](#). In addition, [Figure 3-1](#) shows the corresponding schematic.

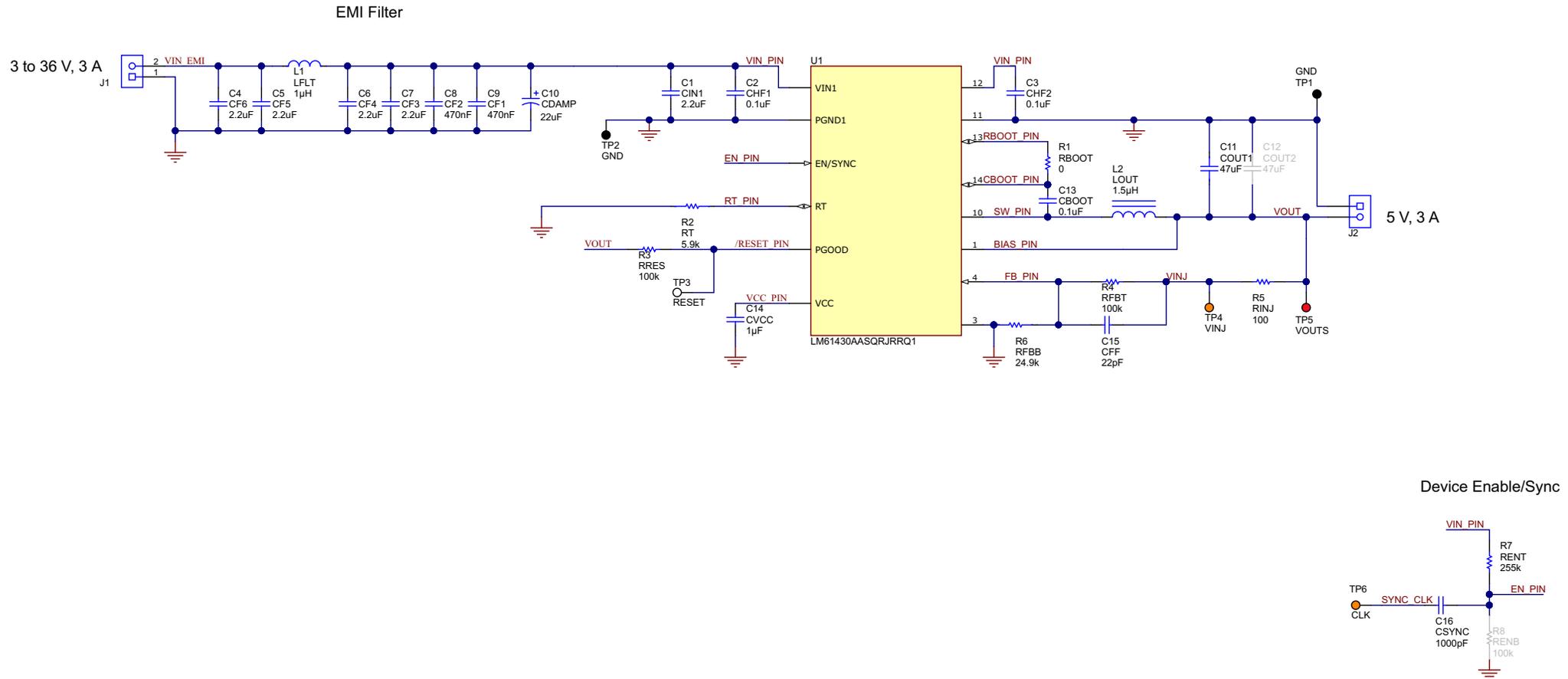


Figure 3-1. LM61430EVM-AS-2MHZ Schematic

4 Board Layout

The PCB consists of a 4-layer design. There are 2-oz copper planes on the top and bottom and 1-oz copper mid-layer planes to dissipate heat with an array of thermal vias to connect to all four layers.

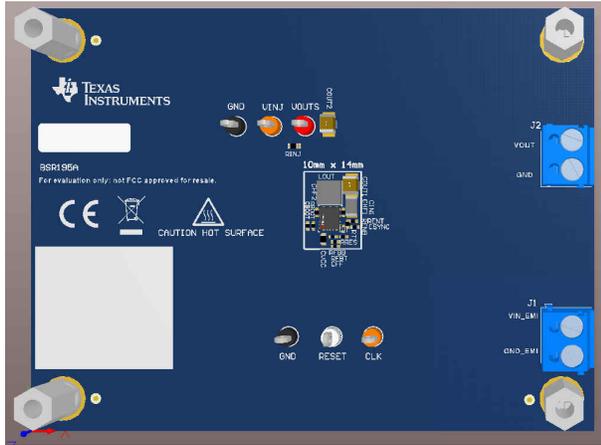


Figure 4-1. Top 3-D View

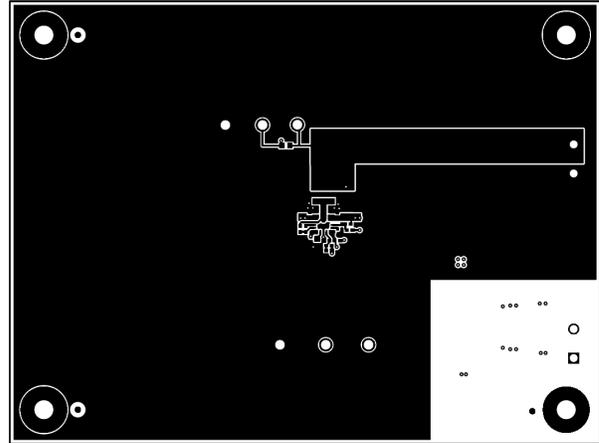


Figure 4-2. Top Layer

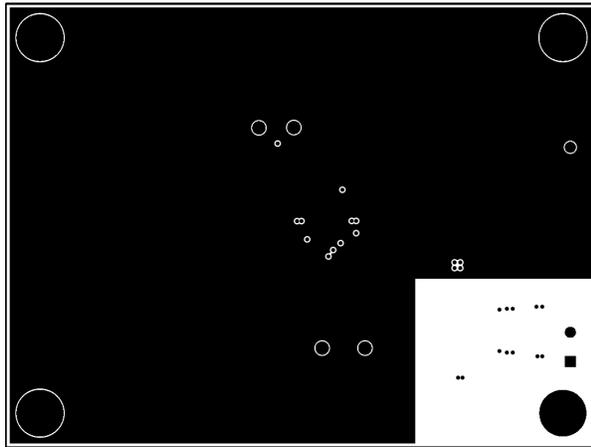


Figure 4-3. Signal Layer 1 – Ground Plane

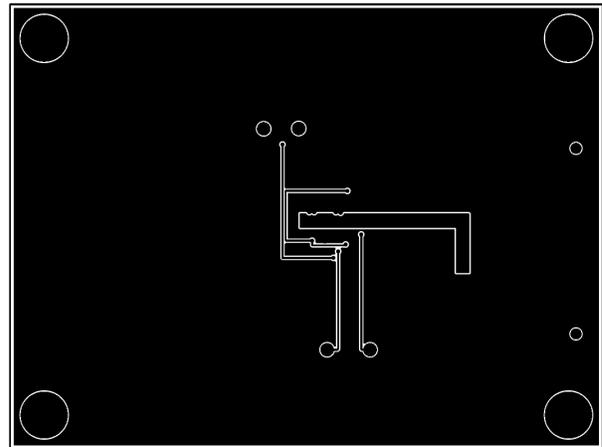


Figure 4-4. Signal Layer 2 – Routing

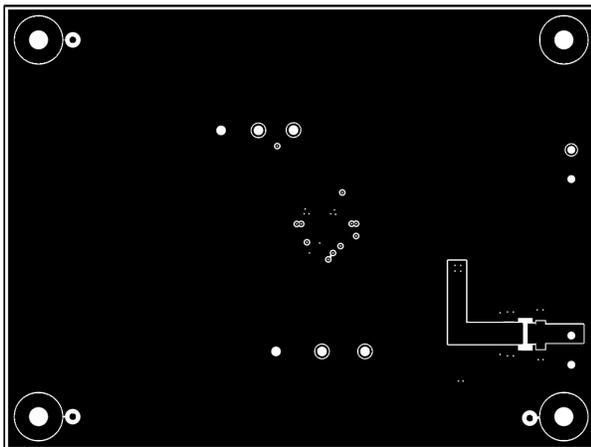


Figure 4-5. Bottom Layer

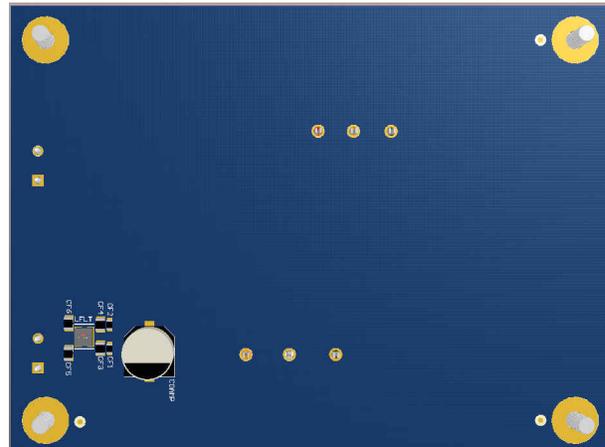


Figure 4-6. Bottom 3-D View

5 Thermal Performance

IC top case measured with 13.5-V input, 5-V output, and 3-A load.

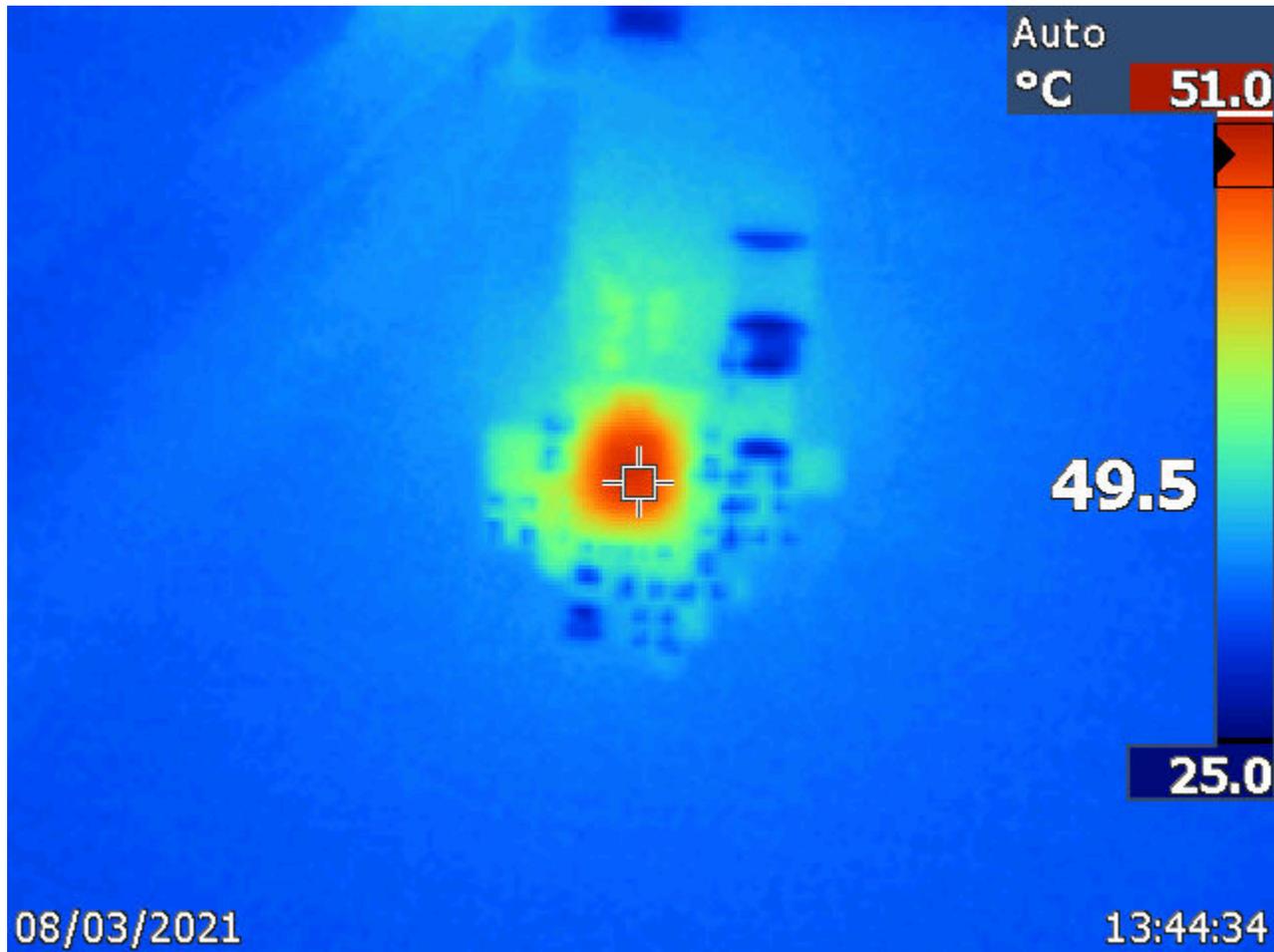


Figure 5-1. Thermal Performance

5.1 Additional Performance Curves

Please reference the [LM61430-Q1 3-V to 36-V, Low EMI Synchronous Step-Down Converter Data Sheet](#) for additional IC performance curves. The data would be located in the application's section of the datasheet being performed on the LM61430EVM-AS-2MHZ.

6 Bill of Materials (BOM)

Table 6-1. LM61430EVM-AS-2MHZ Bill of Materials

DESIGNATOR	QUANTITY	VALUE	DESCRIPTION	PACKAGEREFERENCE	PART NUMBER	MANUFACTURER
C1	1	2.2 μ F	CAP, CERM, 2.2 μ F, 50 V, \pm 10%, X7R, AEC-Q200 Grade 1, 1206	1206	GCM31CR71H225KA55L	MuRata
C2, C3, C13	3	0.1 μ F	CAP, CERM, 0.1 μ F, 50 V, \pm 10%, X7R, AEC-Q200 Grade 1, 0402	0402	GCM155R71H104KE02D	MuRata
C4, C5, C6, C7	4	2.2 μ F	CAP, CERM, 2.2 μ F, 50 V, \pm 10%, X7R, AEC-Q200 Grade 1, 0805	0805	CGA4J3X7R1H225K125AE	TDK
C8, C9	2	0.47 μ F	CAP, CERM, 0.47 μ F, 50 V, \pm 10%, X7R, AEC-Q200 Grade 1, 0603	0603	CGA3E3X7R1H474K080AB	TDK
C10	1	22 μ F	CAP, AL, 22 μ F, 50 V, \pm 20%, 0.7 Ω , SMD	SMT Radial E	EEE-FC1H220P	Panasonic
C11	1	47 μ F	Multilayer Ceramic Capacitor 47 μ F 20% 10 V 1210 T/R	1210	CGA6P1X7S1A476M250AC	TDK
C14	1	1 μ F	CAP, CERM, 1 μ F, 16 V, \pm 10%, X7R, 0603	0603	885012206052	Würth Elektronik
C15	1	22 pF	CAP, CERM, 22 pF, 50 V, \pm 5%, C0G/NP0, AEC-Q200 Grade 1, 0402	0402	CGA2B2NP01H220J050BA	TDK
C16	1	1000 pF	CAP, CERM, 1000 pF, 50 V, \pm 10%, X7R, AEC-Q200 Grade 1, 0402	0402	CGA2B2X7R1H102K050BA	TDK
FID1, FID2, FID3, FID4, FID5, FID6	6		Fiducial mark. There is nothing to buy or mount.	N/A	N/A	N/A
H1, H2, H3, H4	4		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw	NY PMS 440 0025 PH	B&F Fastener Supply
H5, H6, H7, H8	4			Standoff	1902C	Keystone
J1, J2	2		Terminal Block, 5 mm, 2 \times 1, Tin, TH	Terminal Block, 5 mm, 2 \times 1, TH	691 101 710 002	Würth Elektronik
L1	1		1- μ H Shielded Molded Inductor 4-A 32-m Ω , Max 2-SMD	SMD2	74438336010	Würth Electronics
L2	1	1.5 μ H	Inductor, Shielded, Metal Composite, 1.5 μ H, 5.8 A, 0.019 Ω , SMD	4.1 mm \times 4.1 mm	74438356015	Würth Elektronik
LBL1	1			PCB Label 0.650 inch \times 0.200 inch	THT-14-423-10	Brady

Table 6-1. LM61430EVM-AS-2MHZ Bill of Materials (continued)

DESIGNATOR	QUANTITY	VALUE	DESCRIPTION	PACKAGEREFERENCE	PART NUMBER	MANUFACTURER
R1	1	0	RES, 0, 0%, 0.2 W, AEC-Q200 Grade 0, 0402	0402	CRCW04020000Z0EDHP	Vishay-Dale
R2	1	5.9 k	5.9 kΩ, ±1% 0.1W, 1/10W Chip Resistor 0402 (1005 Metric) Automotive AEC-Q200 Thick Film	0402	ERJ-2RKF5901X	Panasonic
R3, R4	2	100 k	RES, 100 k, 0.5%, 0.063 W, AEC-Q200 Grade 0, 0402	0402	CRCW0402100KDHEDP	Vishay-Dale
R5	1	100	RES, 100, 1%, 0.1 W, 0603	0603	RC0603FR-07100RL	Yageo
R6	1	24.9 k	24.9 kΩ ±1% 0.1 W, 1/10W Chip Resistor 0402 (1005 Metric) Automotive AEC-Q200 Thick Film	0402	ERJ-2RKF2492X	Panasonic
R7	1	255 k	RES, 255 k, 1%, 0.063 W, AEC-Q200 Grade 0, 0402	0402	CRCW0402255KFKED	Vishay-Dale
TP1, TP2	2		Test Point, Multipurpose, Black, TH	Black Multipurpose Testpoint	5011	Keystone
TP3	1		Test Point, Multipurpose, White, TH	White Multipurpose Testpoint	5012	Keystone
TP4, TP6	2		Test Point, Multipurpose, Orange, TH	Orange Multipurpose Testpoint	5013	Keystone
TP5	1		Test Point, Multipurpose, Red, TH	Red Multipurpose Testpoint	5010	Keystone
U1	1		3-V to 36-V, Low-EMI Synchronous Step-Down Converter	VQFN-HR14	LM61430AASQRJRRQ1	Texas Instruments
C12	0	47 μF	Multilayer Ceramic Capacitor 47-μF 20%, 10-V, 1210 T/R	1210	CGA6P1X7S1A476M250AC	TDK
R8	0	100 k	RES, 100 k, 0.5%, 0.063 W, AEC-Q200 Grade 0, 0402	0402	CRCW0402100KDHEDP	Vishay-Dale

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2022, Texas Instruments Incorporated